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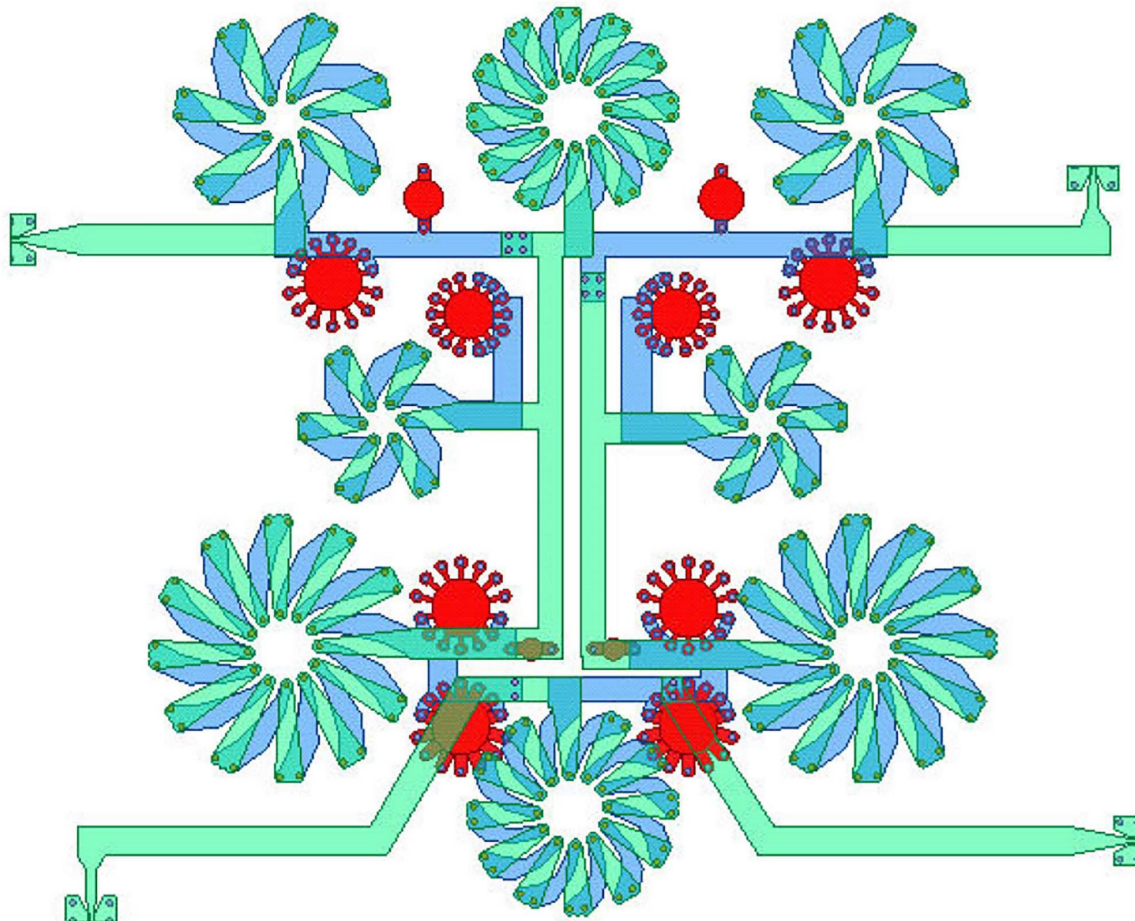
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Cover art from: "Highly Compact VHF/UHF Dual-Band/Dual-Function LTCC Circuits: Application to Avionic Systems" by Seyyed Hassan Mousavi and Ammar B. Kouki (p. 12–22, Fig. 18(a)).



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